



Final Product Change Notification

202103036F01 : TSSOP8 (SOT505-1) Assembly Expansion in ATBK and Manufacturing Alignment

Note: This notice is NXP Company Proprietary.

Issue Date: Oct 06, 2021 **Effective date:** Jan 04, 2022

Here is your personalized notification about a NXP general announcement.
For detailed information we invite you to view this notification online

Management summary

SOT505-1 assembly will be discontinued at ATP and ATBK is adding SOT505-1 assembly to maintain supply.

Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input checked="" type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

PCN Overview

Description

NXP is expanding ATBK assembly capabilities to include the part types in the attached file list. Mold compound and die adhesive materials in the ATBK manufacturing process will use the standard EMC-7470L-Q and QMI519 materials respectively. Additionally, ATBK will employ a roughened leadframe as a package quality improvement to reduce delamination. NXP has extensive manufacturing capabilities in the TSSOP8 family and with the critical demand for these products, these changes will help with timely deliveries. It should be noted that the package offering utilized here will use a Roughened Leadframe solution. While the benefit of the solution is better adhesion of the mold compound (there have been no relevant customer returns).

Reason

Due to increasing demand for SOT505-1 packaged devices, NXP is adding the ATBK flow as an alternate source to help provide timely deliveries.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available from Jul 01, 2021

Production

Planned first shipment Nov 25, 2021

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Nov 05, 2021.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name	Steve Blozis
Position	Marketing
e-mail address	stephen.blozis@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply .

NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006- 2021 NXP Semiconductors. All rights reserved.

Changed Orderable Part#	12NC	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	Product Line
PCF85063ATT/AJ	935304639118	PCF85063ATT/A	Tiny RTC TSSOP8	(T)SSOP8	SOT505-1	RFS	No	BLC6
PCF85263ATT/AJ	935304459118	PCF85263ATT/A	Tiny RTC with Batt switch TSSOP8	(T)SSOP8	SOT505-1	RFS	No	BLC6
PCF85363ATT/AJ	935304751118	PCF85363ATT/A	Tiny RTC Battery switch RAM I2C-bus	(T)SSOP8	SOT505-1	RFS	No	BLC6
PCA8565TS/1,118	935272132118	PCA8565TS/1	RTC	(T)SSOP8	SOT505-1	RFS	No	BLC6
PCF8563TS/4,118	935279522118	PCF8563TS/4	REAL TIME CLOCK/CALENDAR	(T)SSOP8	SOT505-1	RFS	No	BLC6
PCA85063ATT/AJ	935305541118	PCA85063ATT/A	Tiny RTC for automotive	(T)SSOP8	SOT505-1	RFS	No	BLC6
PCA85073ADP/Q900Z	935384764431	PCA85073ADP/Q900	Tiny RTC for auto I2C-bus TSSOP8	(T)SSOP8	SOT505-1	RFS	No	BLC6